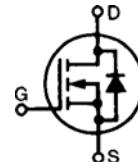


## High Voltage MOSFET

N-Channel, Enhancement Mode

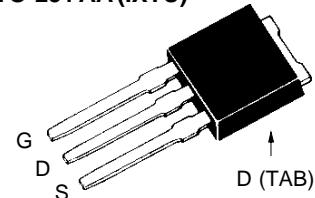
**IXTU 01N80**  
**IXTY 01N80**

$V_{DSS}$  = 800 V  
 $I_{D25}$  = 100mA  
 $R_{DS(on)}$  = 50  $\Omega$

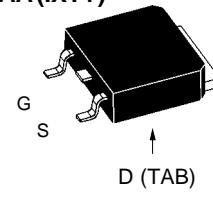


Symbol	Test Conditions	Maximum Ratings 01N100	
$V_{DSS}$	$T_J$ = 25°C to 150°C	800	V
$V_{DGR}$	$T_J$ = 25°C to 150°C; $R_{GS} = 1\text{ M}\Omega$	800	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_c = 25^\circ\text{C}; T_J = 25^\circ\text{C to } 150^\circ\text{C}$	100	mA
$I_{DM}$	$T_c = 25^\circ\text{C}$ , pulse width limited by max. $T_J$	400	mA
$P_D$	$T_c = 25^\circ\text{C}$	25	W
$T_J$		-55 ... +150	°C
$T_{JM}$		150	°C
$T_{stg}$		-55 ... +150	°C
$T_L$	1.6 mm (0.063 in) from case for 5 s	300	°C
<b>Weight</b>		0.8	g

TO-251 AA (IXTU)



TO-252 AA (IXTY)



G = Gate,                    D = Drain,  
 S = Source,                TAB = Drain

Symbol	Test Conditions	Characteristic Values		
		( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	min.	typ.
$V_{DSS}$	$V_{GS} = 0\text{ V}, I_D = 25\text{ }\mu\text{A}$	800		V
$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 25\text{ }\mu\text{A}$	2	4.5	V
$I_{GSS}$	$V_{GS} = \pm 20\text{ V}_{DC}, V_{DS} = 0$		$\pm 50$	nA
$I_{DSS}$	$V_{DS} = 0.8 \cdot V_{DSS}$ $V_{GS} = 0\text{ V}$	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	10 200	$\mu\text{A}$
$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = I_{D25}$ Pulse test, $t \leq 300\text{ ms}$ , duty cycle $d \leq 2\%$		50	$\Omega$

### Features

- International standard packages JEDEC TO-251 AA, TO-252 AA
- Low  $R_{DS(on)}$  HDMOS™ process
- Rugged polysilicon gate cell structure
- Fast switching times

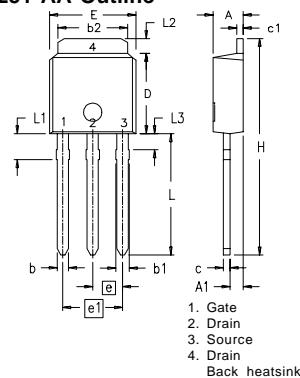
### Applications

- Levelshifting
- Triggers
- Solid state relays
- Current regulators

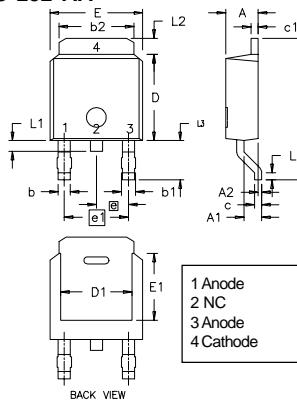
Symbol	Test Conditions	Characteristic Values		
		min.	typ.	max.
$g_{fs}$	$V_{DS} = 10 \text{ V}; I_D = 0.5 \cdot I_{D25}$ , pulse test	140		μS
$C_{iss}$ $C_{oss}$ $C_{rss}$	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	60		pF
		8.0		pF
		2.0		pF
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$	$V_{GS} = 10 \text{ V}, V_{DS} = 500 \text{ V}, I_D = I_{D25}$ $R_G = 50 \Omega$ (External)	12		ns
		12		ns
		28		ns
		28		ns
$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 0.5 I_{D25}$	8		nC
		1.8		nC
		3		nC
$R_{thJC}$			3	K/W

**Source-Drain Diode**

Symbol	Test Conditions	Characteristic Values		
		min.	typ.	max.
$V_{SD}$	$I_F = 100 \text{ mA}, V_{GS} = 0 \text{ V}$ , Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2 \%$		1.5	V
$t_{rr}$	$I_F = 0.75 \text{ A}, -di/dt = 10 \text{ A}/\mu\text{s}$ , $V_{DS} = 25 \text{ V}$		1.5	μs

**TO-251 AA Outline**


Dim.	Millimeter Min. Max.	Inches Min. Max.
A	2.19 2.38	.086 .094
A1	0.89 1.14	.035 .045
b	0.64 0.89	.025 .035
b1	0.76 1.14	.030 .045
b2	5.21 5.46	.205 .215
c	0.46 0.58	.018 .023
c1	0.46 0.58	.018 .023
D	5.97 6.22	.235 .245
E	6.35 6.73	.250 .265
e	2.28 BSC	.090 BSC
e1	4.57 BSC	.180 BSC
H	17.02 17.78	.670 .700
L	8.89 9.65	.350 .380
L1	1.91 2.28	.075 .090
L2	0.89 1.27	.035 .050
L3	1.15 1.52	.045 .060

**TO-252 AA**


Dim.	Millimeter Min. Max.	Inches Min. Max.
A	2.19 2.38	0.086 0.094
A1	0.89 1.14	0.035 0.045
A2	0 0.13	0 0.005
b	0.64 0.89	0.025 0.035
b1	0.76 1.14	0.030 0.045
b2	5.21 5.46	0.205 0.215
c	0.46 0.58	0.018 0.023
c1	0.46 0.58	0.018 0.023
D	5.97 6.22	0.235 0.245
D1	4.32 5.21	0.170 0.205
E	6.35 6.73	0.250 0.265
E1	4.32 5.21	0.170 0.205
e	2.28 BSC	0.090 BSC
e1	4.57 BSC	0.180 BSC
H	9.40 10.42	0.370 0.410
L	0.51 1.02	0.020 0.040
L1	0.64 1.02	0.025 0.040
L2	0.89 1.27	0.035 0.050
L3	2.54 2.92	0.100 0.115

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

 4,835,592 4,881,106 5,017,508  
 4,850,072 4,931,844 5,034,796

 5,049,961 5,187,117 5,486,715 6,306,728B1  
 5,063,307 5,237,481 5,381,025